

Nanocrystal based memory Design : Application of semiconductor electrostatics

Feb 12, 2024

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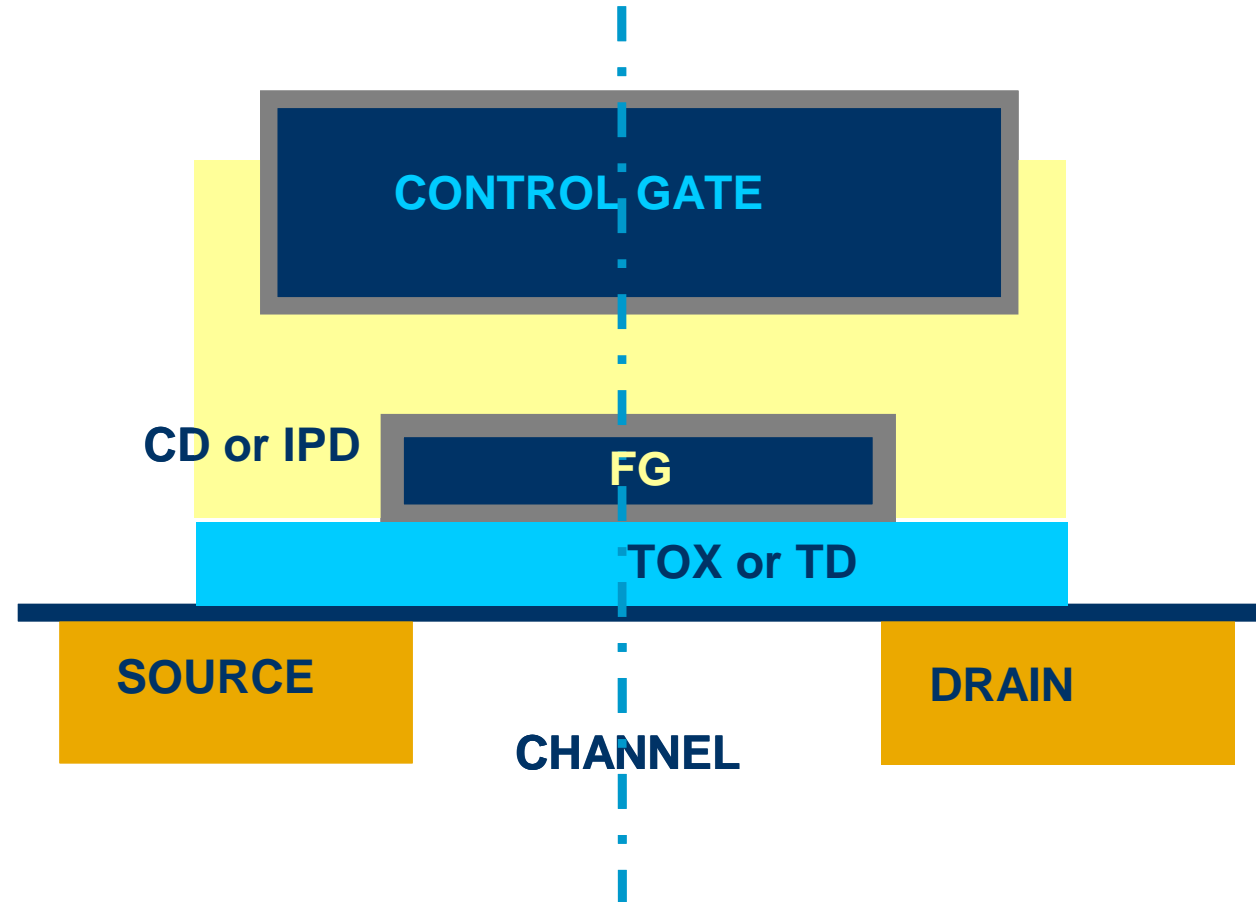
Reference: A simple FG Flash memory tutorial

<https://www.youtube.com/watch?v=s7JLXs5es7I>

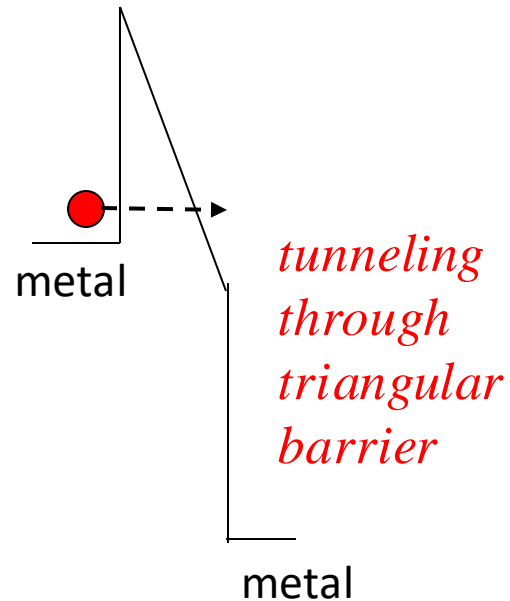
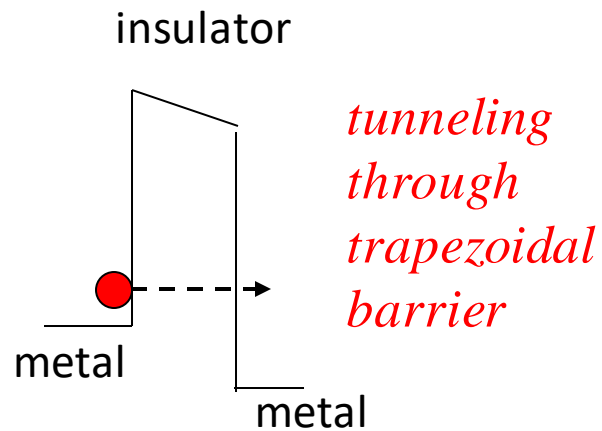
The CNT vs planar FET based nanocrystal memory study is taken from this paper

<https://doi.org/10.1109/TNANO.2006.888529>

Background: A memory transistor: Floating Gate Flash



New Physics: Tunneling



Electron as a wave can “tunnel” through barriers!

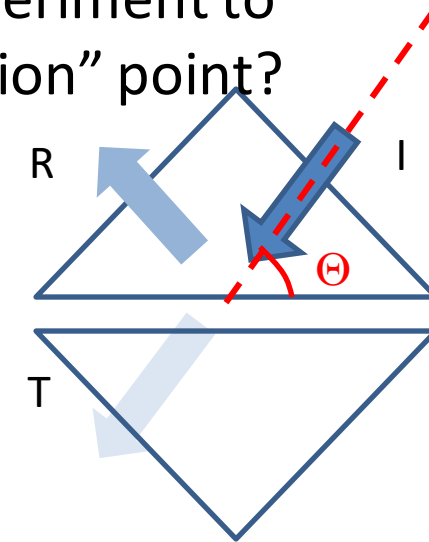
Any wave can tunnel!

The light analogy:

If we place a prism with light and go beyond a critical angle Θ we get Total Internal Reflection

Think: Where does the light “decide” to turn around? (a) At (b) before (c) after the interface (d) irrelevant?

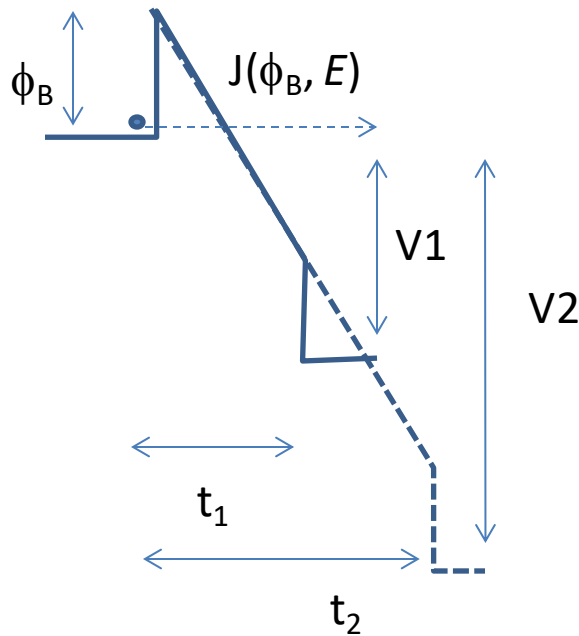
Pair: What is an experiment to measure this “decision” point?



Result: Light decays exponentially in the gap!

A bit more on Tunneling

We have 2 capacitors made of Pt/SiO₂ / Pt with oxide thickness t_1 and t_2 respectively.



Think: Is the current V dependent?

Pair: If the barrier is triangular, can I claim

(a) Current Density (J) depends only on V and ϕ_B

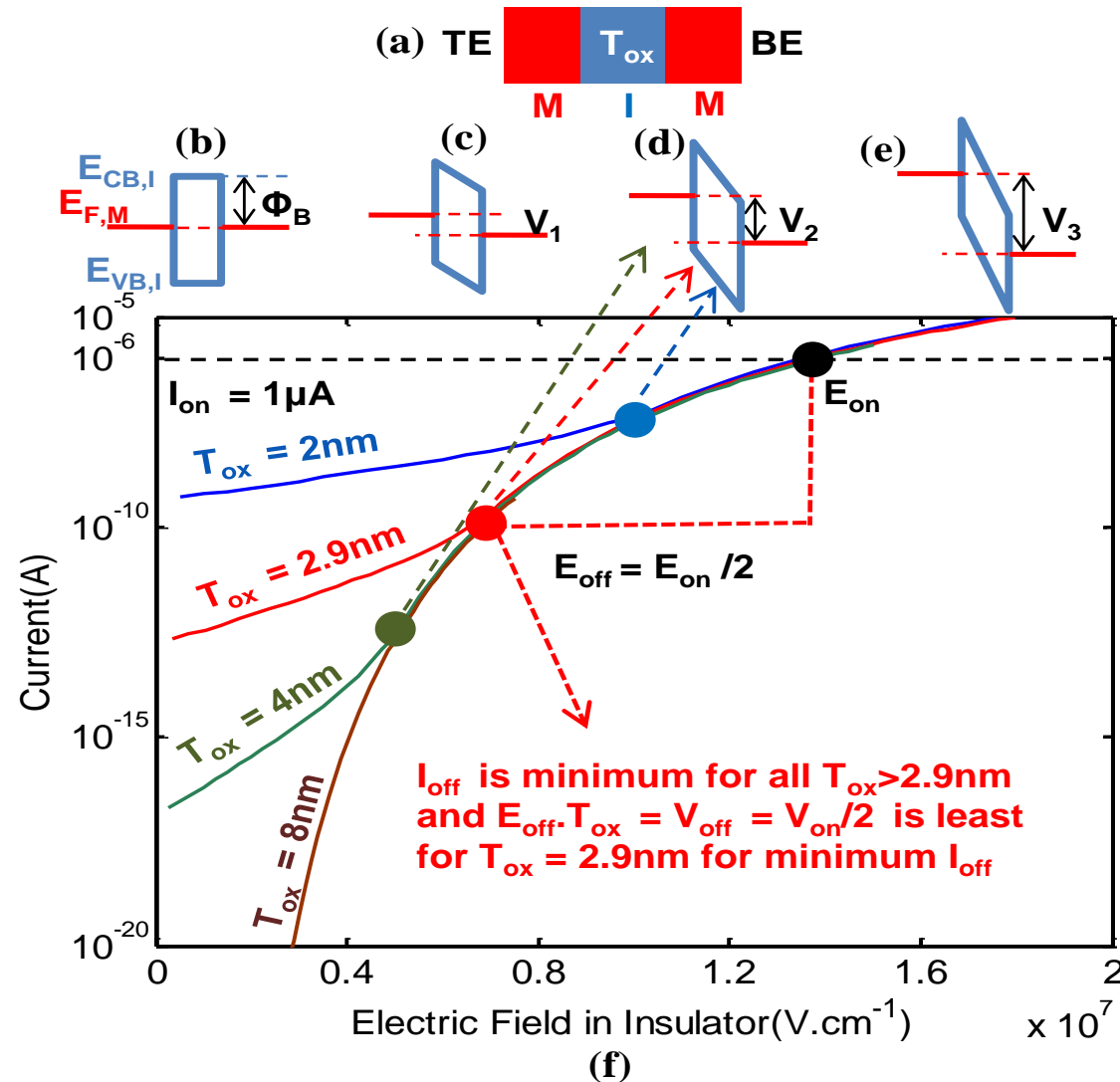
(b) Current Density (J) depends only on Electric field and ϕ_B

(c) Current Density (J) depends only on V and Electric field

State the basis of the choice & elimination?

Bias can modulate the “transparency” of the barrier to electron tunneling $J(\phi_B, E) \rightarrow$ exponential function!

DT and FN comparison

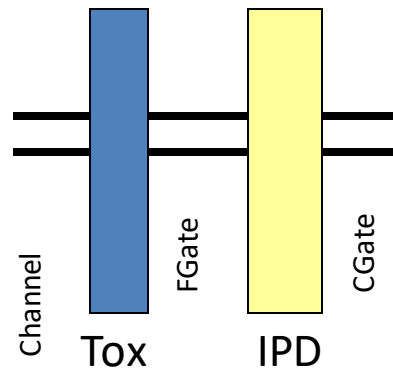


Since both DT and FN is exponential in E field we can use a simple current addition of FN and DT.

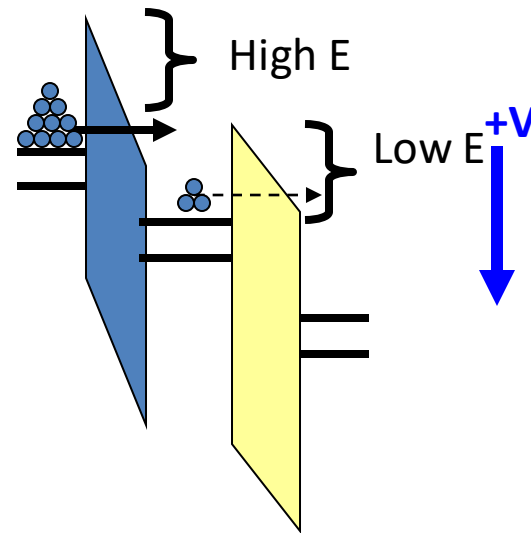
Approximation is valid because only one function will dominate – except in the small transition region

DT is also thickness dependent – so it dominates FN for thinner oxides

Flash Memory Operation



1. Fresh device

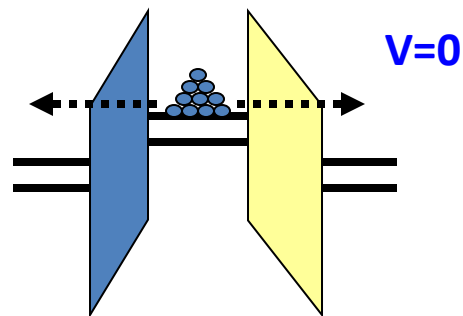


2. Program

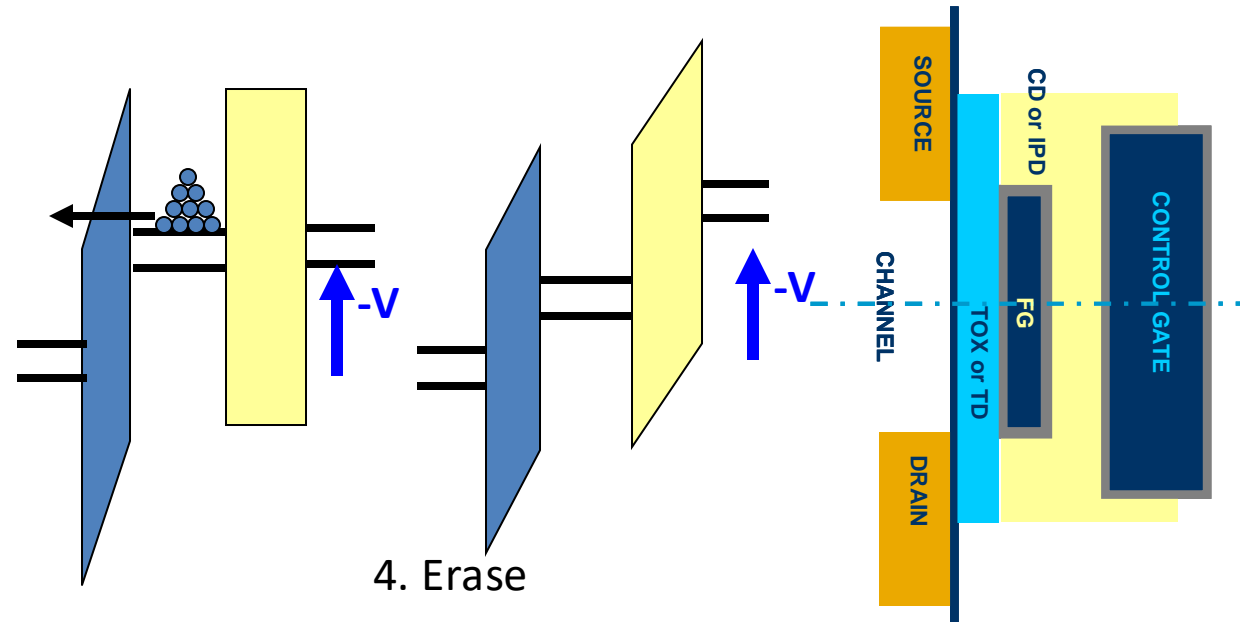
•>Tox

•> IPD

Inter poly
dielectric
(Al_2O_3)



3. Retention

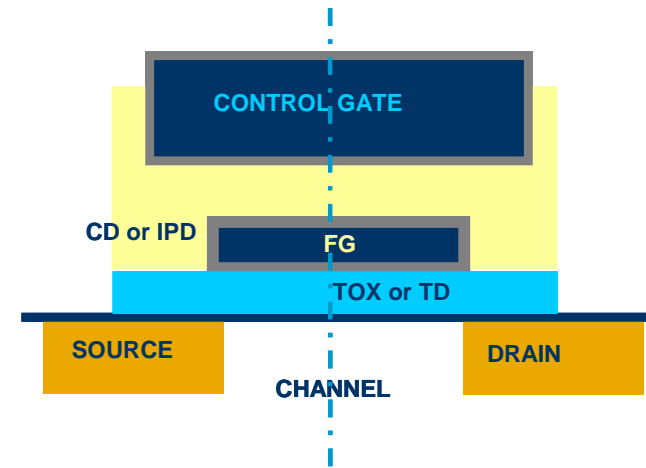


4. Erase

Assume: Tunneling is exponential with electric field;

Write down the requirements of tunnel oxide vs. IPD for
Prog (18V) vs Retention (0V) to set the thickness

- IPD
- Tun Ox



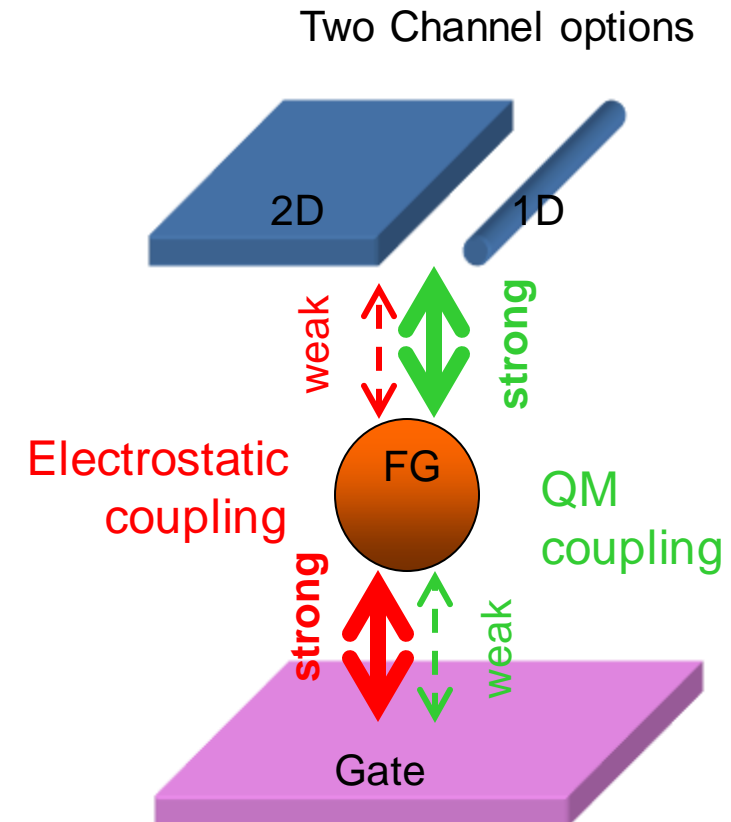
- Is there a dilemma or a design challenge?

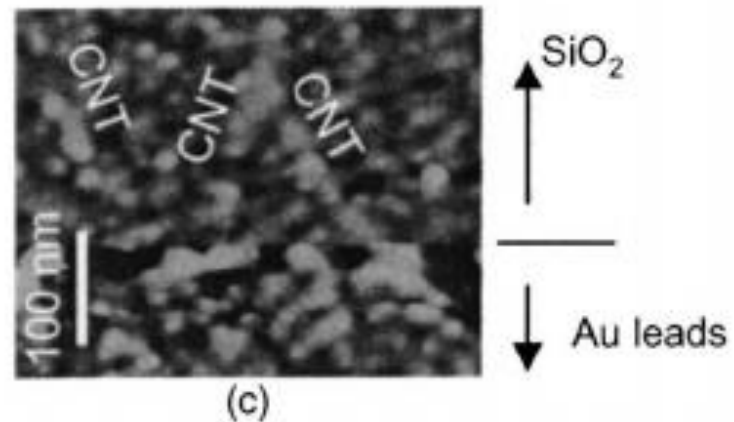
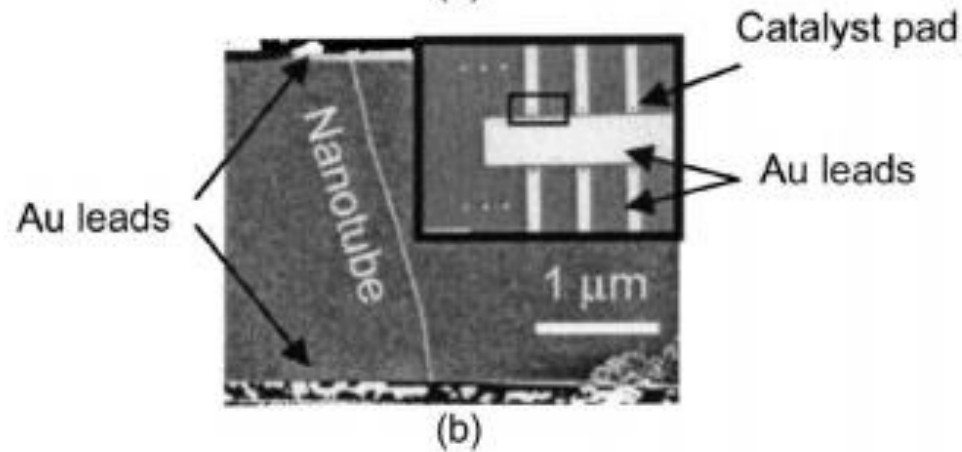
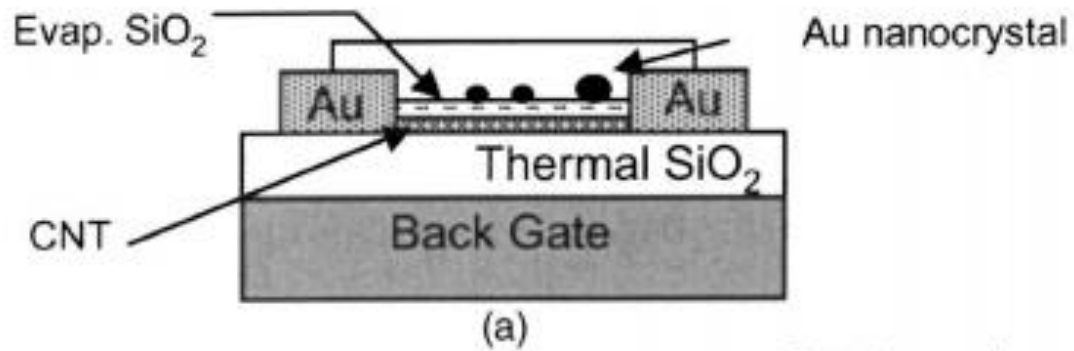
Answer in the next slide; do not turn until
you have spent 10 min to write this down

Dilemma in Memory Design

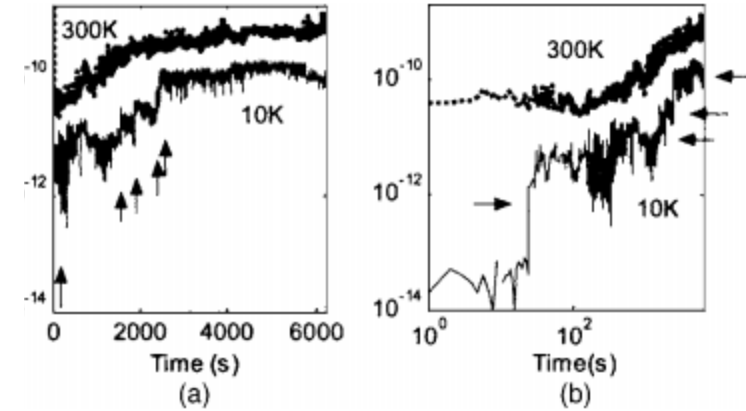
- Electrostatic coupling
 - NC-GATE
- Quantum Mechanical coupling
 - NC-Channel

Both tunneling and electrostatics are function of distance

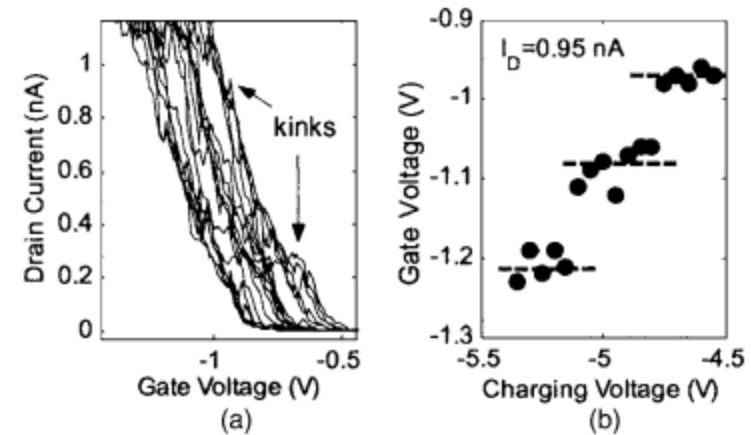




IV characteristics (an example)



Single electrons can jump out of the nanocrystal



Single electrons can jump into the nanocrystal

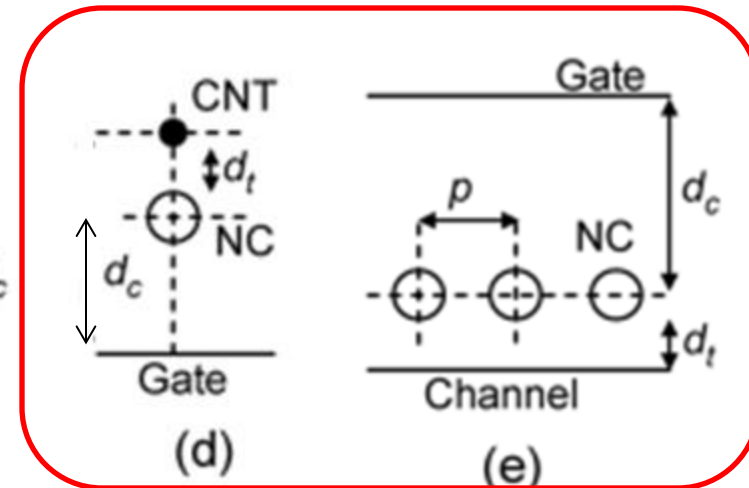
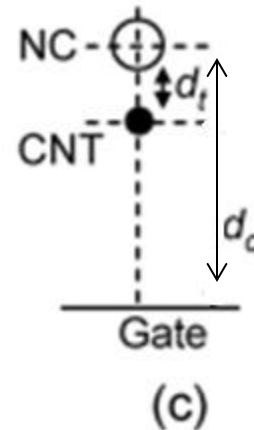
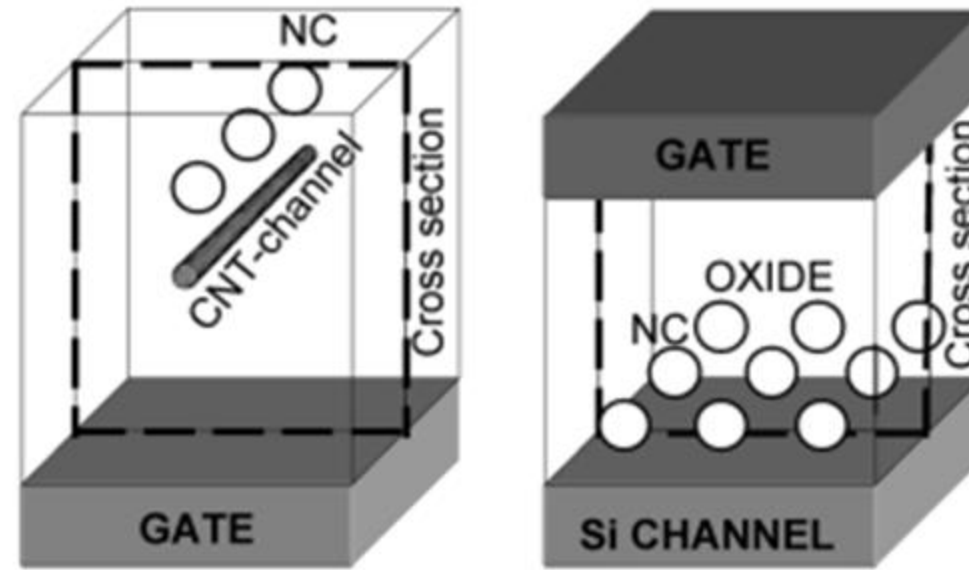
NC based memory

Technology Options:

1. Carbon Nanotube channel- Metal NC
2. Si channel- Metal NC

Operation (requirement):

1. Program/ Erase : Fast @ $\pm 20V$
2. Retention: Slow @ 0V but NC has stored electronic charge



Which one will produce a better performance?

Answer in the next slide; do not turn until you have spent 20 min to write this down

How to proceed?

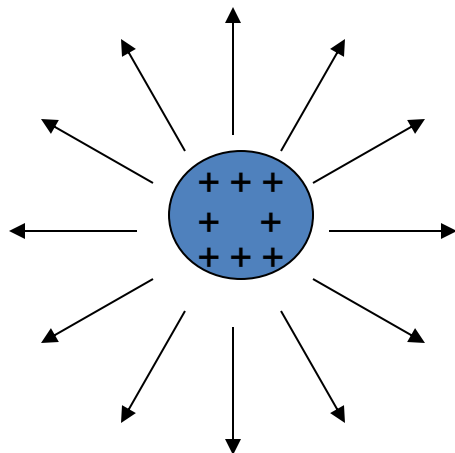
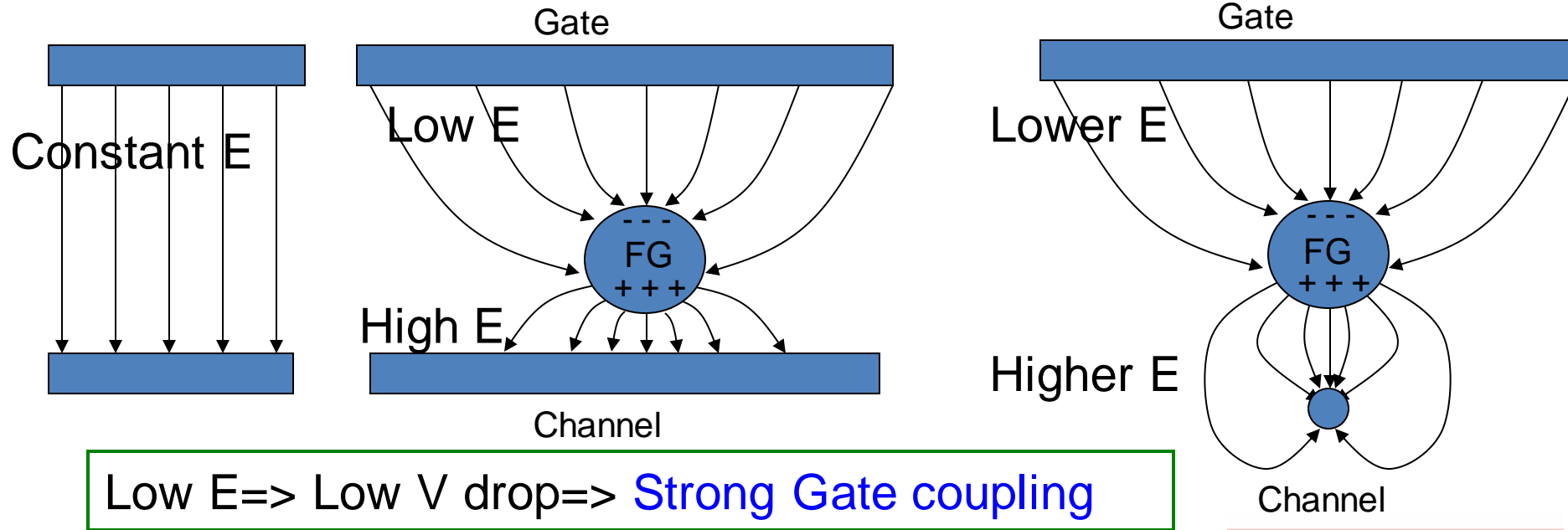
- Can we understand the capacitive coupling difference in the two systems
 - In program
 - During retention

PROGRAM CONDITION

➤ Channel ON

➤ assume METALLIC

1D vs. 2D channel

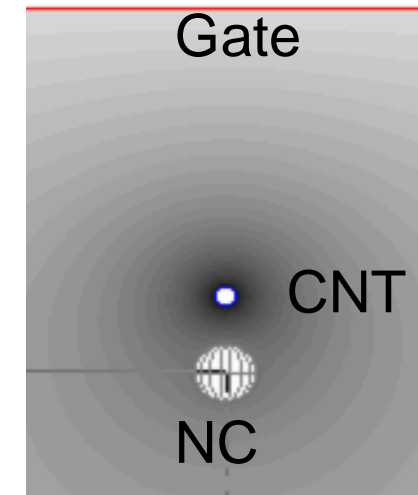


Self Capacitance

➤ $E \sim 1/r^2$

➤ Not affected by surroundings

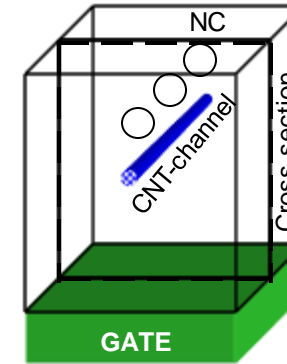
U. Ganguly et al, T Nano, 2006



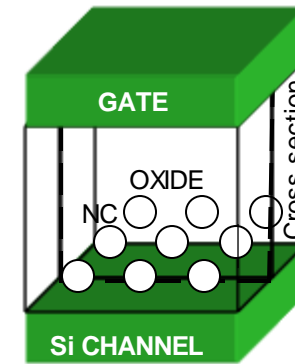
Program

Simulation results to validate the model

Structural Parameters		Potential on NC (V)	
	d_c (nm)	Capacitive Coupling $V_G=5$	Self Capacitance $q_{NC}=5e$
1NC-CNT BG	21	2.52	-0.517
	30	2.35	-0.519
	100	1.77	-0.528
1NC-CNT TG	30	2.69	-0.509
3NC-CNT BG	30	2.33	-0.68
1 NC-Si		0.81	-0.46
3×3 NC -Si		0.74	-0.67

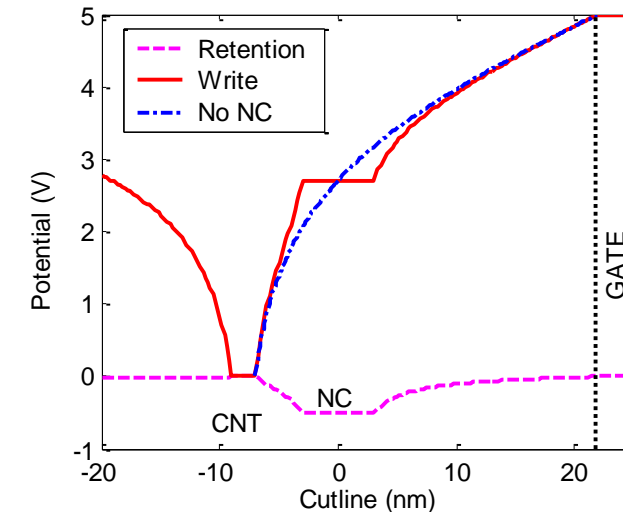


CNT (1-D) channel



Si (2-D) channel

Large electric fields than 2D Si channel!!!



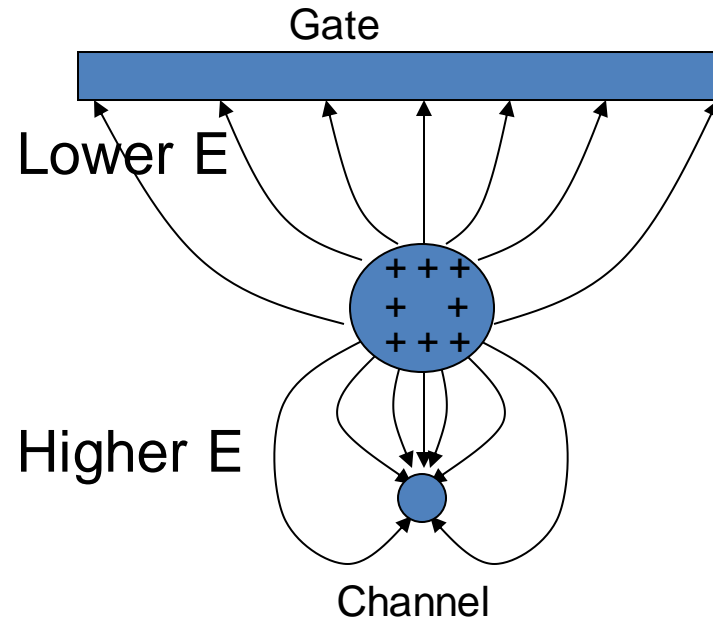
~ 15e

~ 5e

Retention Condition

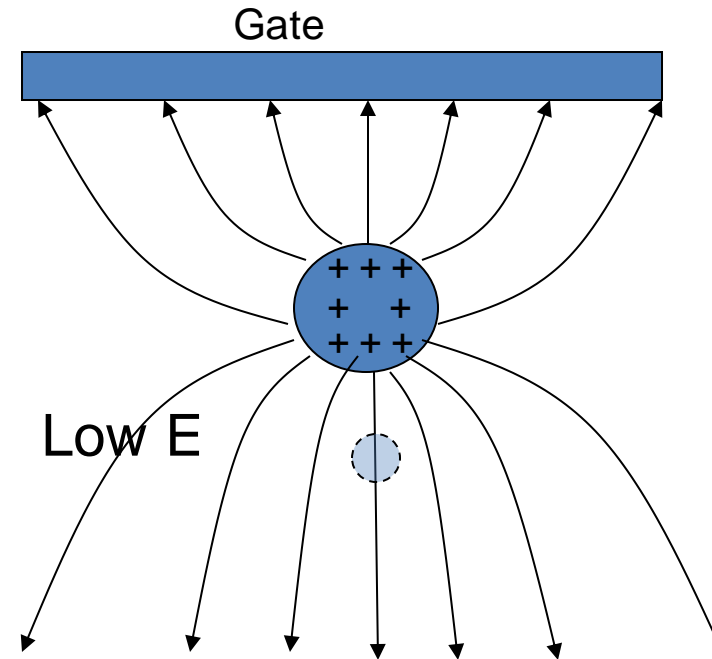
➤ Channel OFF

➤ assume DIELECTRIC



Metallic Channel

Retention

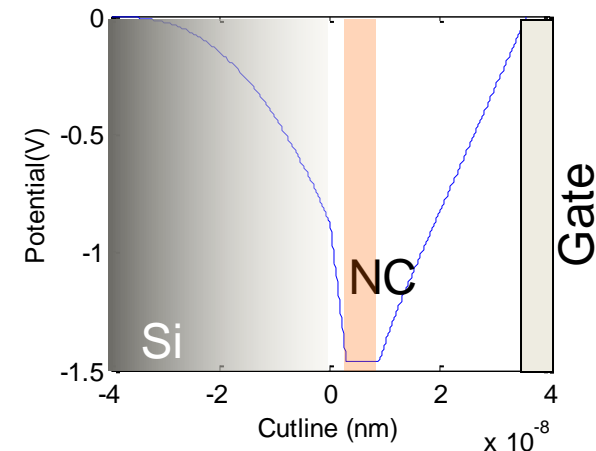
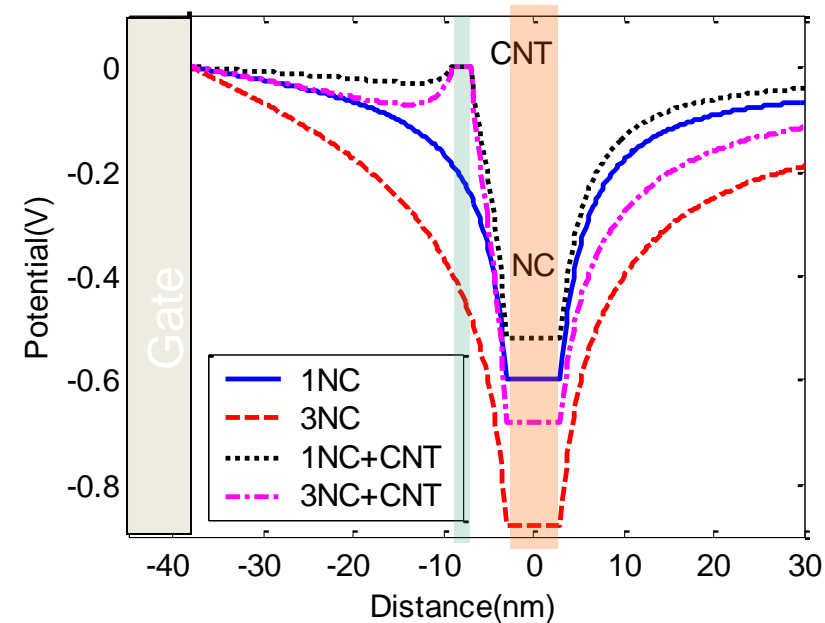


Dielectric Channel

Retention

- In this case, CNT is a conveniently a dielectric
 - 1NC case -0.35V
 - 3NC case -0.39V
- 2D Si channel
 - 1NC case -0.46V (Si: metallic)
 - 3x3 NC case -0.67V (Si: metallic)
 - NC array case -0.58V (doping $1 \times 10^{18} \text{cm}^{-3}$)
- CNT metallic
 - 1NC case -0.51V
 - 3NC case -0.68V

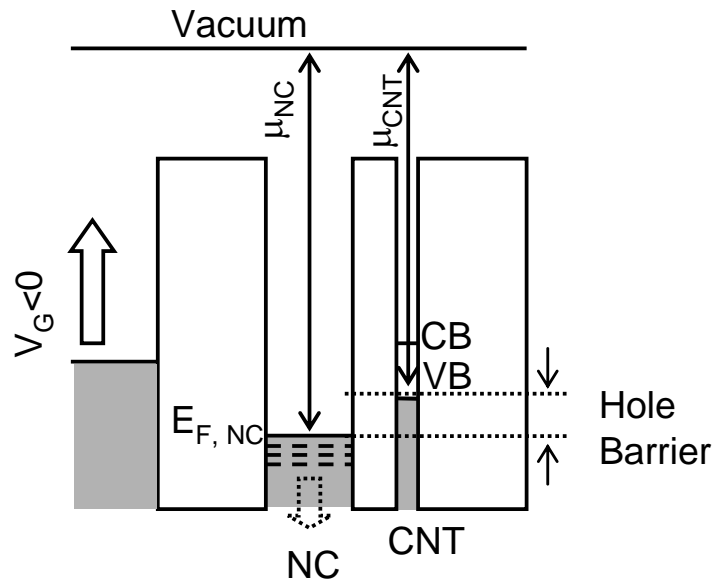
40% reduction in electric fields with CNT



Charge injection at $V_{CH}=5V$

From experiment

- Total V_T shift of 1.24 V
- V_T shift of 130mV per electron
- 9.4 electrons storage detected (incredibly large electron # for 5V charging!!!)
- ΔV_{CH} per electron $\sim 0.4V$



✓ Validation is OK

✓ Explains large # of electrons

✓ Slightly lower experimental value is due to read disturbance

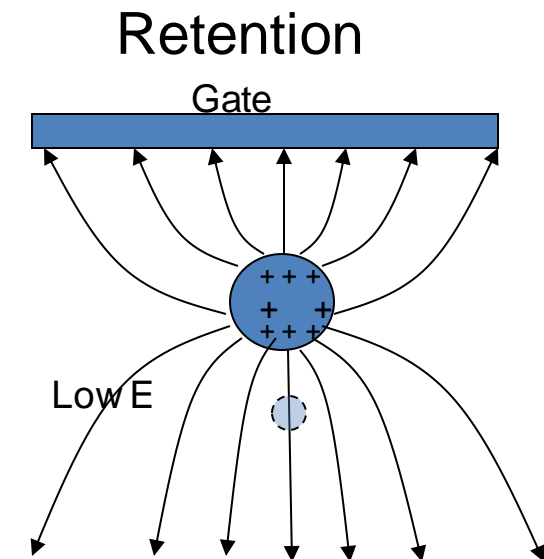
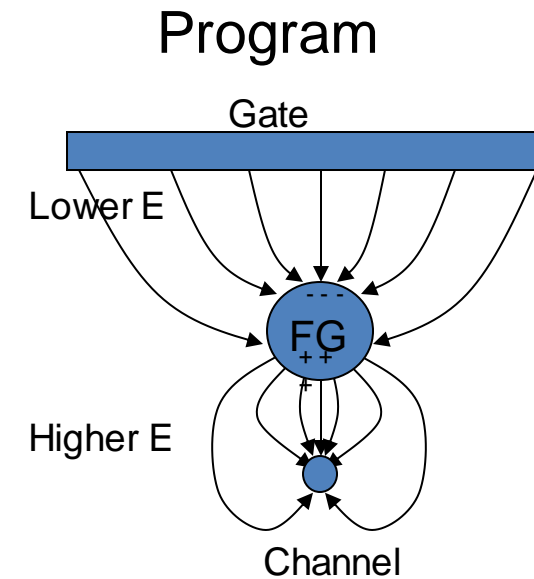
Validation

From theory

- Total hole well depth 1.26V
 - Gate bias 5V \Rightarrow NC is at 1.86V
 - Band offset correction of 0.6V i.e. Au 5.1eV, CNT valence band ~ 4.5 eV
- Self capacitance energy 104 meV
 1. Max electrons that can be stored ~ 12 (c.f. 5 electrons in 2D channel)
 2. ΔV_{CH} per electron $\sim 0.42V$ (from gate coupling calculations)

Results

- Ideal structure for electrostatics
 - Strong gate coupling
 - High write field (FN tunneling) 3-4x larger
 - 40% lower retention field
- => Better Write/retention ratio possible
- <5V operation inspite of thick gate stack
- 3x number of electron per NC compared



Questions for conceptual reinforcement

- In this class, we worked on a “judge” type question – the highest skill level in learning! To reflect on the process, here are a few practice questions.
- Write down the steps of approaching the problem – like a computer algorithm. e.g.
 - What is the goal? tunneling rate control
 - what is that main metric of success? electric field
 - How to evaluate/ judge this?..
 - ...
 - Conclusion
- For Program and Erase Case
 - Present the key arguments for program case –
 - state in 1 sentence the associated principle learnt in class for each argument
 - state the final conclusion;
 - can you validate quantitatively with simplifying assumptions?

Solving any such unstructured problem

Steps

- Step 1: Define the critical physical phenomenon
- Step 2: Define model

Example

- Transport in low V (retention) vs high V (Program) states needs to be modeled
- Given we only know in tunneling $J \sim \exp(k\vec{E})$, we need to model \vec{E}
- Given structure, model $\vec{E}(x, y)$;

Solving any such unstructured problem

Steps

- Step 3: Define metric of comparison
- Step 4: Make a judgement
- Step 5: Validate

Example

- We need to compare J at high vs. low V . Which $\vec{E}(x, y)$ affects tunneling? Decide/guess that \vec{E} at the injecting surface matters. Compare this.
- Compare the \vec{E} at relevant surface and judge
- Either use expt or simulation to test model and conclusions